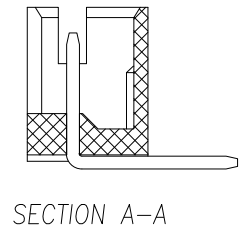
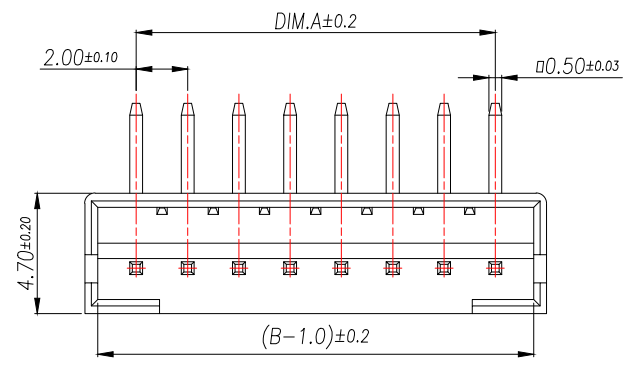
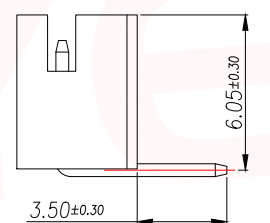
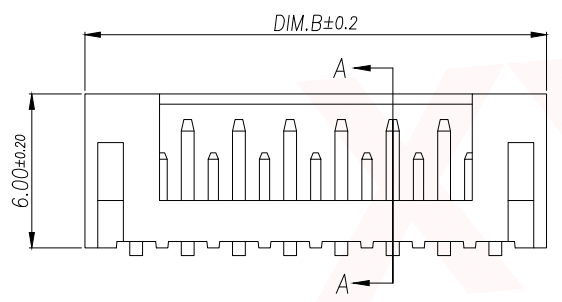


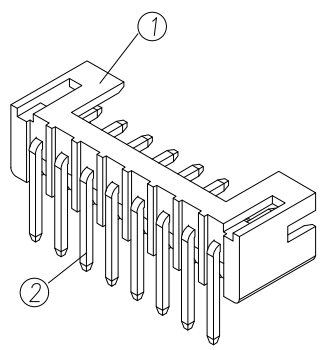
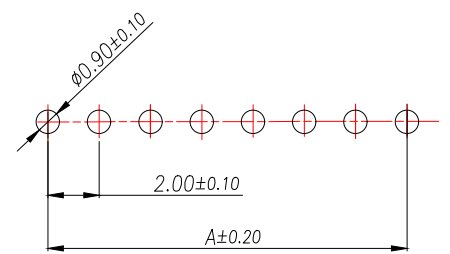
PRELIMINARY
DESIGN IS SUBJECT
TO CHANGE WITHOUT
PRIOR NOTICE



- 技术要求:
- 1、塑件材料:PA66 (UL-94V-0)
 - 2、接触件:黄铜镀锡
 - 3、接触电阻: ≤10mΩ
 - 4、绝缘电阻: ≥1000MΩ
 - 5、额定电压: 250V AC DC
 - 6、额定电流: 2.0A AC DC
 - 7、耐压: 能承受1000V AC/Min ute
 - 8、工作温度: -25°~+85°
 - 9、可焊性试验: 浸锡面积≥95% 温度220±5°, 时间 2.5±0.5秒
 - 10、铅和镉等六大有害物质含量要符合环保要求



Part No	PIN	A	B
XY-PH2.0-2A21	2	2	6
XY-PH2.0-3A21	3	4	8
XY-PH2.0-4A21	4	6	10
XY-PH2.0-5A21	5	8	12
XY-PH2.0-6A21	6	10	14
XY-PH2.0-7A21	7	12	16
XY-PH2.0-8A21	8	14	18
XY-PH2.0-9A21	9	16	20
XY-PH2.0-10A21	10	18	22
XY-PH2.0-11A21	11	20	24
XY-PH2.0-12A21	12	22	26
XY-PH2.0-13A21	13	24	28
...
XY-PH2.0-20A21	20	(20-1)*2	(20+1)*2



2	Contact	Brass	n*1	电镀(锡): 整个表面镀底镍30u"MIN,再镀锡80u".MIN.
1	Wafer	PA66(UL94V-0)	1	本色
序号	名称	材料	数量	备注

厦门市辛译精密电子有限公司
Xiamen XinYi Xyconn Electronics Co.,Ltd

DIMENSION IN mm		APR. Alex		TITLE: WAFER 2.0mm H6.0mm 90° DIP	
TOLERANCE UNLESS OTHERWISE SPECIFIED		CHK. Jack		DWG NO. XY-PH2.0-NA21	
.X±0.35	X.*± 5°	DRA. Can		PROJ. CUSTOMER DRAWING	
.XX±0.25	.X.*± 3°	SIZE A4	SCALE 1:1	SHEET 1/1	REV. A
.XXX±0.15	.XX.*± 1°				